

A detailed cross-sectional diagram of a multi-layered device, likely a semiconductor or microelectronic component. The diagram shows several layers and internal structures. Key components are labeled with numbers: 1 (outermost layer), 2 (layer below 1), 3 (central cavity or channel), 4 (top layer on the right), 5 (two horizontal bars within the central cavity), 6 (layer below 2), 7 (bottom layer), 8 (two horizontal bars within the bottom layer), 9 (layer below 6), 10 (a small rectangular feature at the bottom right), 11 (a small rectangular feature at the top left), 12 (a small rectangular feature at the bottom left), and 13 (a small rectangular feature at the top right). Arrows labeled 'III' point upwards from the bottom layer (7) towards the central cavity (3). The diagram uses various hatching patterns to distinguish between different materials or layers.

FIG. 3

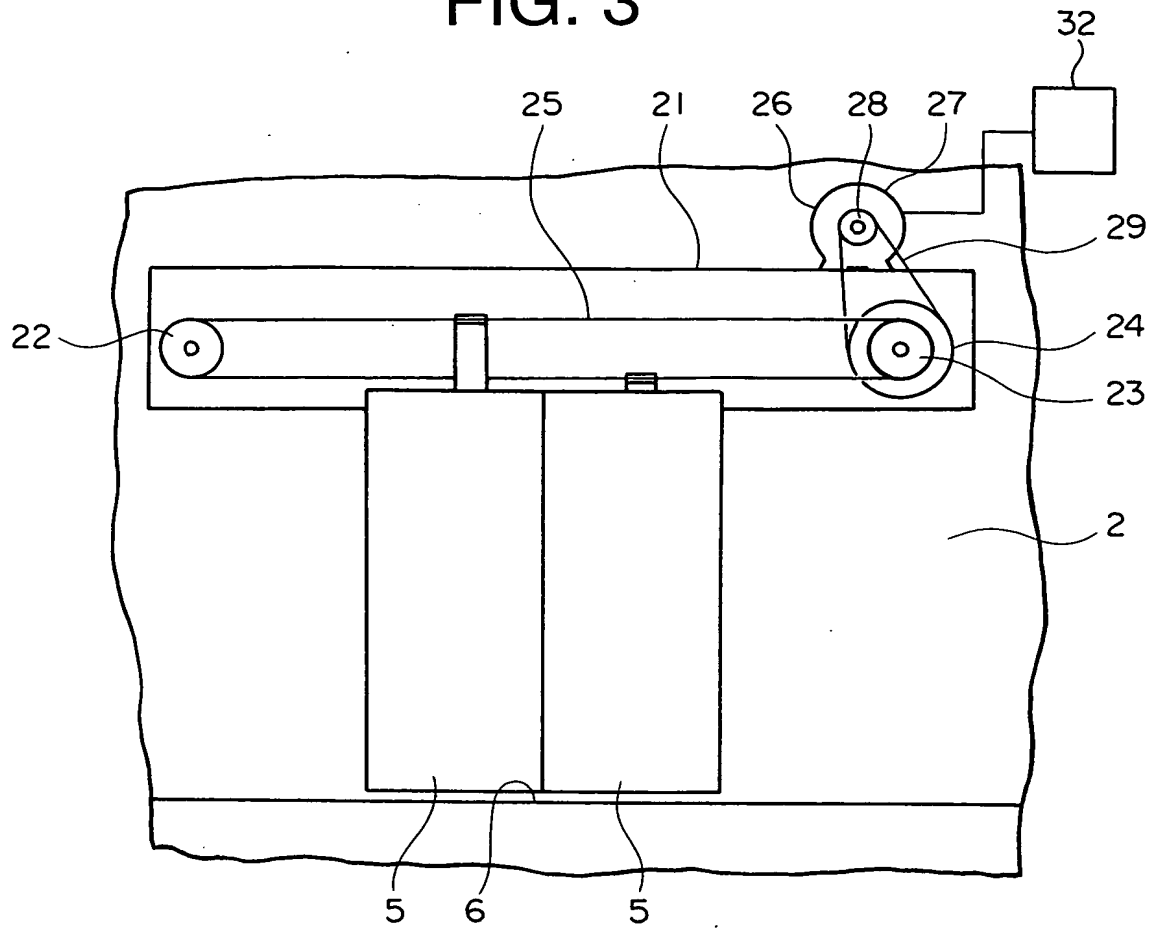


FIG. 4

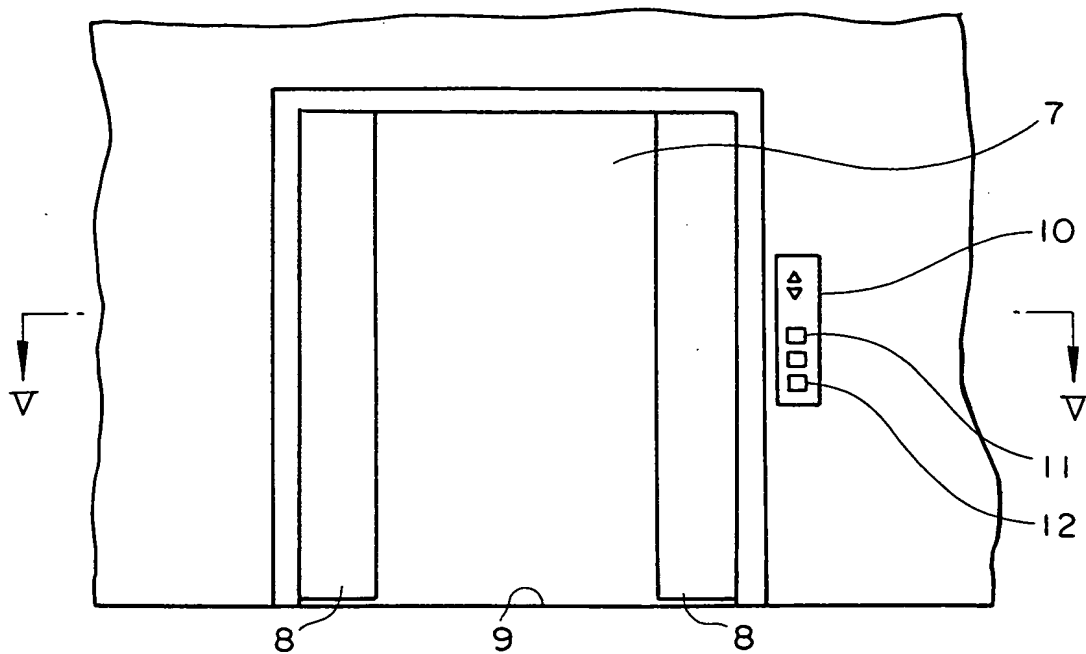


FIG. 5

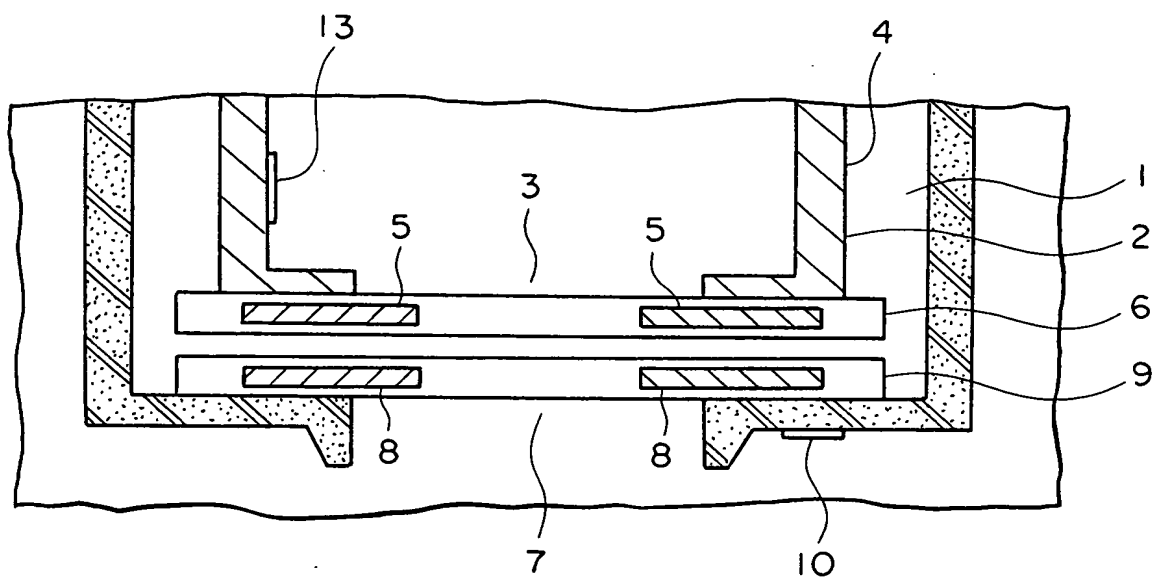


FIG. 6

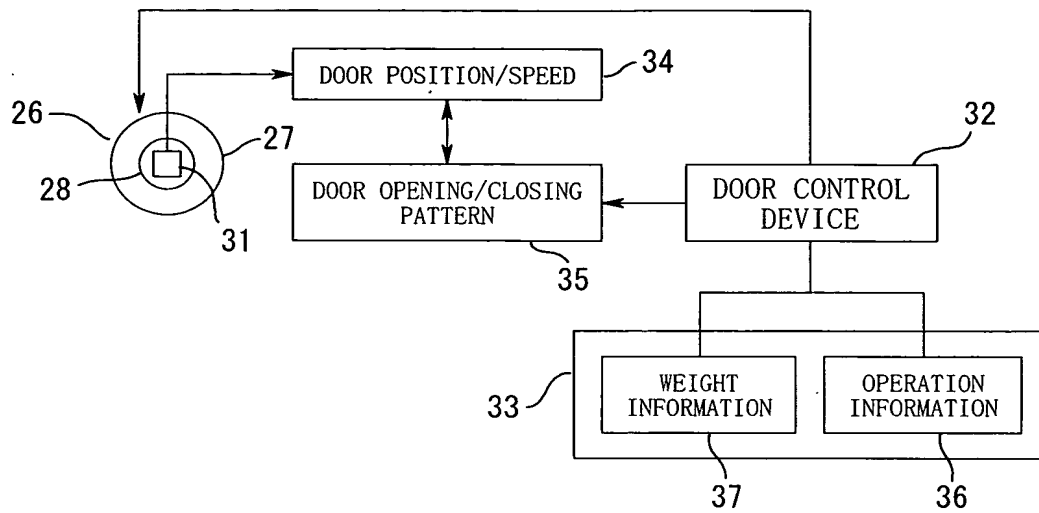


FIG. 7

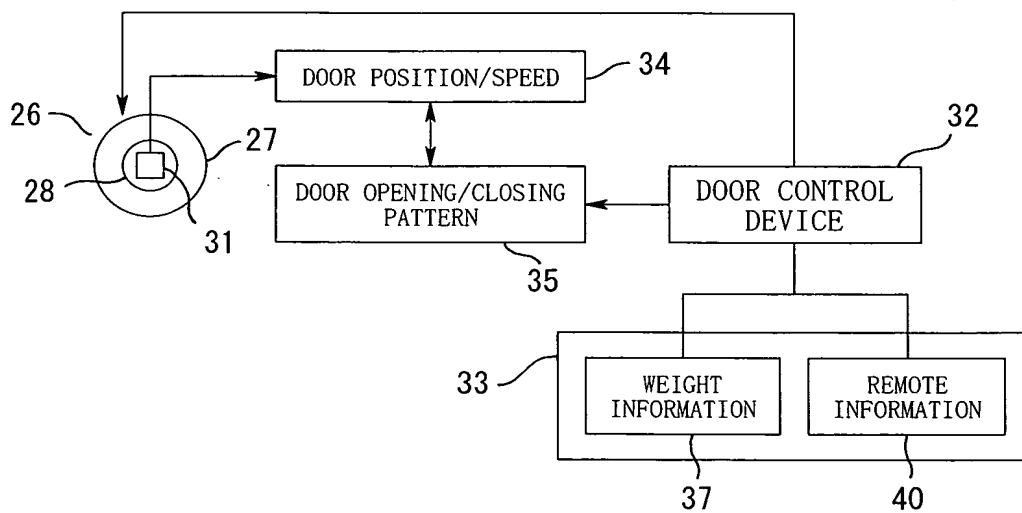


FIG. 8

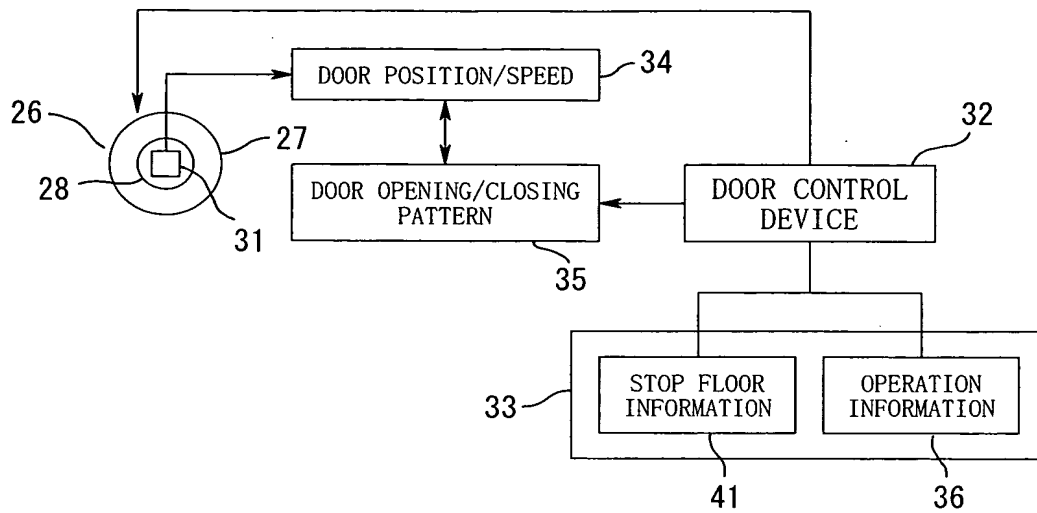


FIG. 9

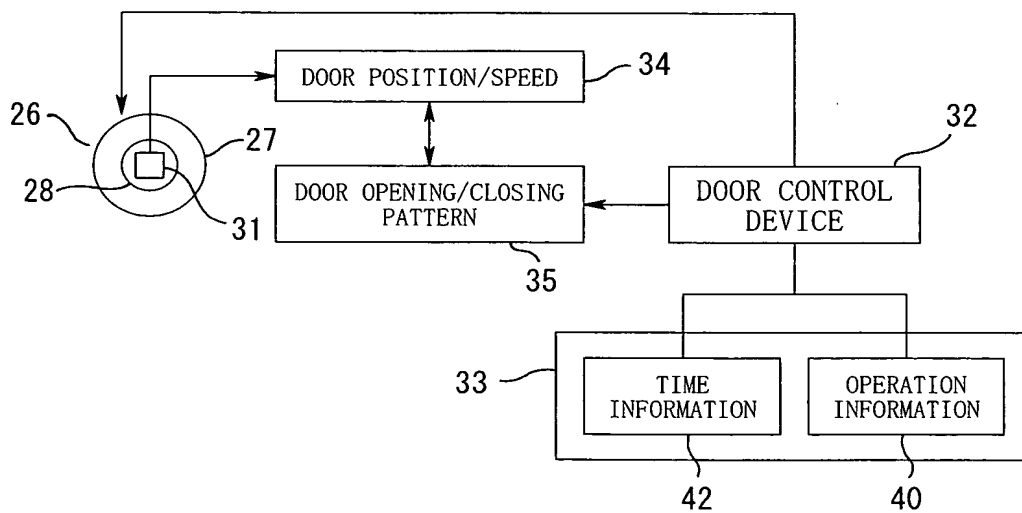


FIG. 10

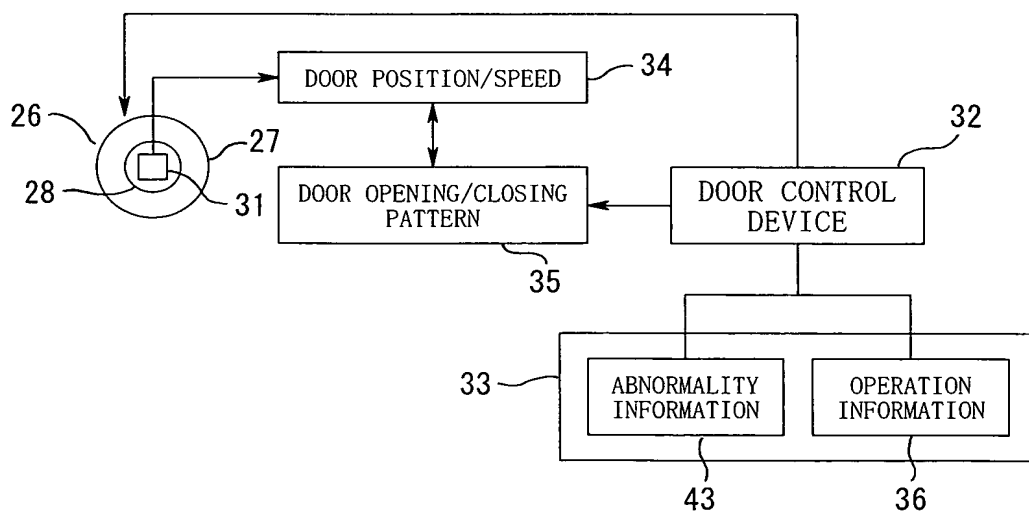


FIG.11

